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Supplementary Information

Deformable and Highly Adhesive Poly(ionic liquid)/Liquid

Metal Visco-Elastomers for Thermal Management

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Fig. S1 DSC curve of P[OVIm]NTf_2 bulk material in the temperature range of -50 to 150 °C.



Fig. S2 GPC curves of $P[OVIm]NTf_2$ in two solvents, DMF and DMSO.



Fig. S3 Demonstration of the stretching process of $P[OVIm]NTf_2$ visco-elastomers.



Fig. S4 SEM image of $P[OVIm]NTf_2/LM$ (39 vol%) visco-elastomers.



10µm



Fig. S5 Elemental distribution mapping of $P[OVIm]NTf_2/LM$ (39 vol%) visco-elastomers.



Fig. S6 Elemental distribution mapping of P[OVIm]NTf₂/LM (66 vol%) visco-elastomers.



Fig. S7 A comparison of thermal decomposition curves for three proportions under a nitrogen atmosphere, within a temperature range of 20-700 $^{\circ}$ C.



Fig. S8 Optical microscopy images of the $P[OVIm]NTf_2$ self-healing process.



Fig. S9 The mechanical tensile properties of $P[OVIm]NTf_2$ before and after self-healing.



Fig. S10 GPC curves of low MW $P[OVIm]NTf_2$ in two solvents, DMF and DMSO.



Fig. S11 Diagram of Test Method for Interface Adhesion Performance.



Fig. S12 Interface adhesion strength test at different temperatures for $P[OVIm]NTf_2$.